

Features

- Frequency range : 20MHz to 66MHz
- Ultra compact and thin
- AuSn sealing, ceramic SMD package
- External dimensions (mm)
L : 1.6 x W : 1.2 x H : 0.35
- RoHS compliant & Pb free

Applications

- BT, BLE, W-LAN, NFC
- SiP modules
- Mobile phone, Wearables
- Internet of Things (IoT)
- Portable consumer products

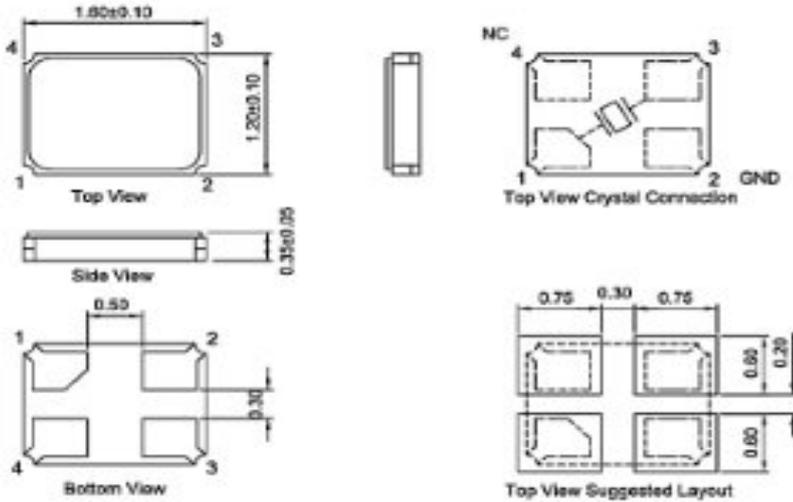
Electrical Characteristics

Item		8Q	Conditions
Frequency Range	F_0	20MHz ~ 66MHz	
Frequency Tolerance	F_{tol}	±30ppm, ±20ppm, ±10ppm	at 25°C
Frequency Stability over Operating Temperature Range (refer to 25°C)	F_{stab}	±30 ppm	-20°C ~ +70°C
		±20 ppm	
		±10 ppm	
		±10 ppm	-30°C ~ +85°C
		±30 ppm	-40°C ~ +85°C
		±20 ppm	
Operating Temperature Range	T_{OTR}	-20°C ~ +70°C	
		-40°C ~ +85°C	
		-40°C ~ +125°C	
Shunt Capacitance	C_0	3pF Max.	
Drive Level	D_L	1 ~ 200µW (50µW Typ.)	
Load Capacitance	C_L	6pF, 7pF, 8pF, 9pF, 10pF, 12pF, 16pF, 18pF	
Aging	F_{aging}	±3 ppm Max.	at 25°C ± 3°C, first year
Storage Temperature Range	T_{STR}	-55°C ~ +125°C	

Motional Resistance (ESR)

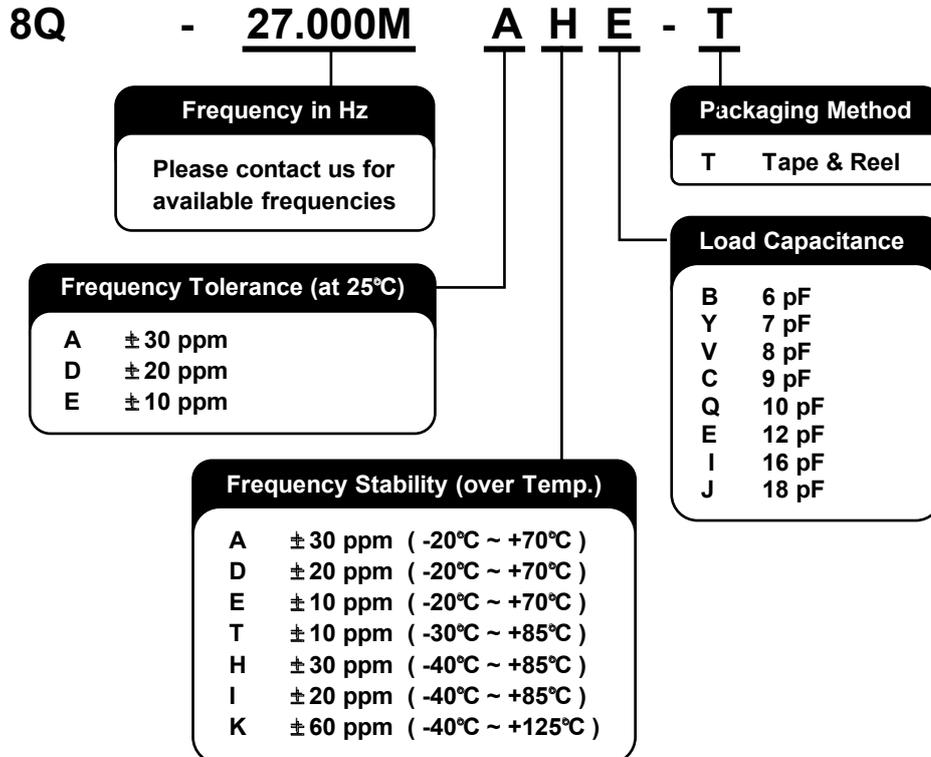
Fundamental	
20 ~ 30 MHz	100Ω Max.
30 ~ 66 MHz	80Ω Max.

Dimensions

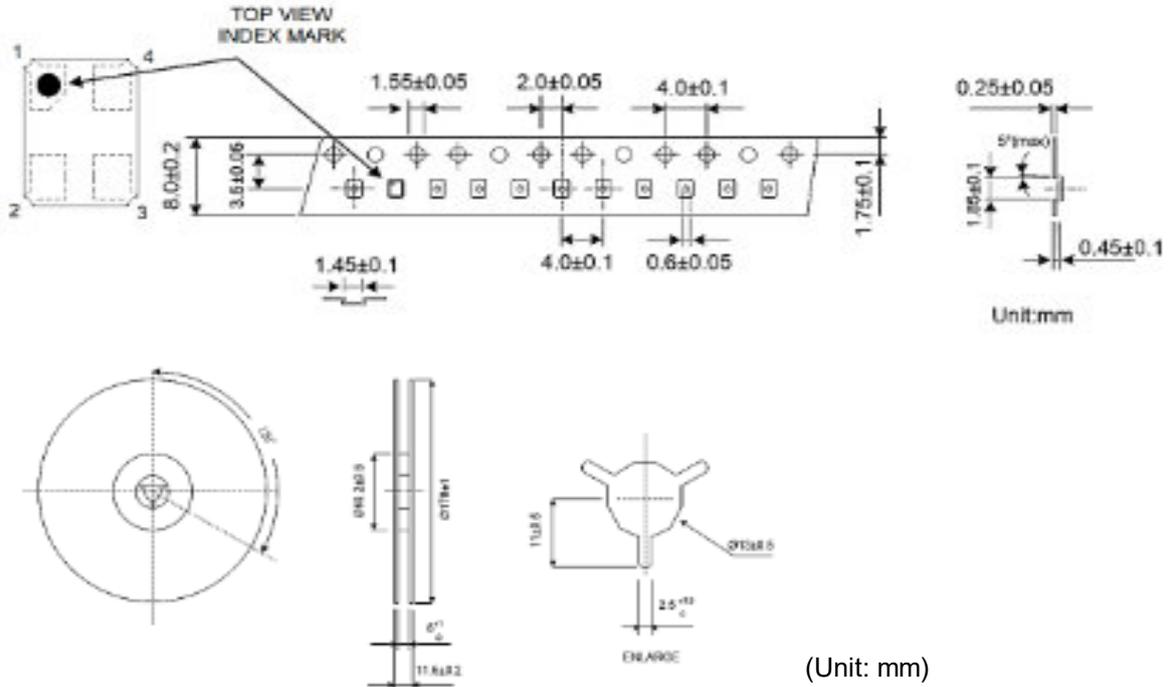


(Unit: mm)

Ordering Information



Packing



Reflow Profile

Solder melting point : 220°C ± 10°C, 60 sec. Min.

Peak temperature : 260°C ± 10°C, 10 sec. Min.

